

## REMARKS

### Claim Amendments

Claims 1 and 2 have been amended. Claims 3-12 were previously canceled. New claims 13-35 have been added

It is respectfully submitted that the amendments to independent claims 1 and 2 and the addition of new claims 13-35 do not introduce new matter into the above-referenced application.

Independent claim 1 has been amended to remove limitations on the thicknesses of various elements recited in the claim. Support for the removal of these limitations is provided at col. 4, lines 10-15, of U.S. Patent 5,291,061, which indicates that these limitations are merely preferred embodiments, and that other "various modes of carrying out the principles disclosed ... are contemplated as being within the scope of the ... claims." The other revisions to independent claim 1 merely correct grammatical and typographical errors and improve consistency.

Independent claim 2 has also been amended to remove limitations on the thickness of various elements recited therein. Again, col. 4, lines 10-15, of U.S. Patent 5,291,061 provides support for the removal of these unnecessary limitations. In addition, independent claim 2 has been revised to replace "wherein a total encapsulation-layer height is about 0.070 inches" with "wherein a total encapsulated package height is at most about 0.070 inches," support for which is provided by U.S. Patent 5,291,061 at col. 3, lines 51-54, and in independent claim 2. The other revisions to independent claim 2 merely correct grammatical and typographical errors and improve consistency.

New claims 13-35 have been added to the above-referenced application.

New claim 13 is an independent claim drawn to a semiconductor device package that includes a stacked assembly of a carrier, at least four semiconductor dice, and dielectric adhesive elements. *See, e.g.*, U.S. Patent 5,291,061, FIG. 2; col. 2, line 60, to col. 3, line 25 (which also provides support for the conductive elements of the semiconductor device package of independent claim 13); col. 3, lines 51-54. In addition, the semiconductor device package includes an encapsulant, which surrounds the stacked assembly. *See, e.g.*, FIG. 2; col. 3, lines 25-26. A combined thickness of the stacked assembly and the encapsulant is no greater than 0.110 inch. Col. 2, lines 14-19. U.S. Patent 5,291,061, in FIG. 2 and at col. 2, line 60, to

col. 3, line 26, also provides support for all of the other subject matter recited by new independent claim 13.

Support for all of the subject matter recited by new claims 14-21, which depend from new independent claim 13, is also provided by the specification of U.S. Patent 5,291,061. *See* FIG. 2 and col. 2, line 60, to col. 3, line 26.

New claim 22 is an independent claim that is also directed to a semiconductor device package that includes a stacked assembly of a carrier, at least four semiconductor dice, and dielectric adhesive elements. *See, e.g.*, U.S. Patent 5,291,061, FIG. 2; col. 2, line 60, to col. 3, line 25 (which also provides support for the conductive elements of the semiconductor device package of independent claim 22); col. 3, lines 51-54. In addition, the semiconductor device package includes an encapsulant, which surrounds the stacked assembly. *See, e.g.*, FIG. 2; col. 3, lines 25-26. A combined thickness of the stacked assembly and the encapsulant is no greater than 0.110 inch. Col. 2, lines 14-19. U.S. Patent 5,291,061, in FIG. 2 and at col. 2, line 60, to col. 3, line 26, also provides support for all of the other subject matter recited by new independent claim 22.

Support for all of the subject matter recited by new claims 23-27, which depend from new independent claim 22, is also provided by the specification of U.S. Patent 5,291,061. *See* FIG. 2 and col. 2, line 60, to col. 3, line 26.

New claim 28 is an independent claim that recites a semiconductor device with a carrier, a first semiconductor die, and a second semiconductor die. *See, e.g.*, U.S. Patent 5,291,061, FIG. 2; col. 3, lines 51-54. Adhesives secure the first semiconductor die to the carrier and the second semiconductor die to the first semiconductor die. FIG. 2; col. 3, lines 35-37. The thickness of the adhesive that secures the second semiconductor die to the first semiconductor die is about 0.001 inch to about 0.005 inch. Col. 3, lines 35-37.

Claim 33 adds semiconductor dice to the assembly of independent claim 28. FIG. 2; col. 3, lines 27-44. Claim 34 recites that first and third sets of bond wires having substantially the same lengths. FIG. 2 (bond wires 30A coupled to semiconductor dice 20 and 16. Claim 35

similarly recites that the second and fourth sets of bond wires have substantially the same lengths. FIG. 2 (bond wires 30A coupled to semiconductor dice 18 and 12).

Support for all of the other subject matter recited by new independent claim 28, as well as for all of the subject matter recited by claims 29-33, which depend from new independent claim 28, is also provided by the specification of U.S. Patent 5,291,061. *See* FIG. 2 and col. 2, line 60, to col. 3, line 26.

#### **Assent of Assignee**

A new Assent of Assignee to Reissue, which complies with the requirements of 37 C.F.R. §§ 1.172(a) and 3.73, is being submitted with this Amendment.

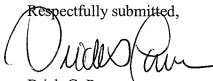
#### **Reissue Declaration**

A new Reissue Declaration, which complies with the requirements of 35 U.S.C. § 251 and 37 C.F.R. § 1.175, is also being submitted with this Amendment.

### CONCLUSION

It is respectfully submitted that each of claims 1, 2, and 13-35 is allowable. An early notice of the allowability of each of these claims is respectfully solicited, as is an indication that the above-referenced application has been passed for issuance. If any issues preventing allowance of the above-referenced application remain which might be resolved by way of a telephone conference, the Office is kindly invited to contact the undersigned attorney.

Respectfully submitted,



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